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EXAMINER

LIEW, ALEX KOK SOON

ART UNIT

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PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

1. The amendment filed on 3/27/08 is entered and made of record.

2. Response to Applicant's Arguments:

I. On page 2 of the reply, the applicant stated: "Regarding claims 1 and 5, neither Tsujikawa or Kishimoto discloses, teaches or renders obvious that the inspection data is generated by classifying and grouping solder element shape and position data corresponding to a plurality of pattern holes into at least one data group which is grouped according to a grouping condition apart from other data group, wherein the grouped data is identified by the grouping condition." The examiner disagrees; there are two grouping condition in Kishimoto: first shown in figure 3, where a plurality of chips are grouped together and other shown in figure 17, where each chip is grouped individually. As discussed by the applicant the first grouping method divides the circuit board into areas to be viewed, wherein the divided circuit information are 'data,' which read on the current claimed language (column 5, lines 4-11) and this 'data' is use in inspection. Also in figure 3, each of the grouped circuit and grouped to away from each other, 3-1, 3-2, 3-3 and 3-4. In regards to claim 'classifying' language, the two types of grouping condition in Kishimoto read on it.

The arguments presented by the applicant are not convincing and examiner will repeat the same rejection from previous office action.

DETAILED ACTION

Claim Rejections - 35 USC § 103

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. Claims 1 – 8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsujikawa (US pat no 5,991,435) in view of Kishimoto ('224) and official notice (MPEP 2144.03).

With regards to claim 1, Tsujikawa discloses Tsujikawa discloses a printing inspection apparatus for inspecting a printing state of cream solder on a substrate after screen printing, said apparatus comprising image pick-up means for picking up an image of said substrate (see figure 14, 53) and printing judging means for making a go/no-go judgment of the printing state based on an image pick-up result of said substrate from said image pick-up means and inspection data needed to perform a printing inspection (see col. 6 lines 29 to 36, if the cream solder covers over a certain amount of area then it is classified as failure otherwise it non-defective), but does not disclose grouping means for classifying and grouping the element position data into data groups which are grouped according to a grouping condition to identify at least one data group according to the grouping condition apart from other data group than the data group grouped. Also one skilled in the art would include a step of grouping plurality of grouped holes because to ensure proper alignment and placement of each electronic component onto the electronic board.

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Kishimoto reads on inspection data is generated by classifying and grouping solder element shape and position data corresponding to a plurality of patterns into at least one data group which is grouped according to a grouping condition apart from other data group, wherein the grouped data is identified by grouping condition (there are two different grouping condition discussed in Kishimoto; see figure 3 for first grouping condition, where a plurality of chips are grouped together; see figure 17, where each chip is group individually, discussed on column 5, lines 1 to 11, this grouping reads on the grouping conditions of the current invention, also chips inherently have electrodes/leads in order for them to be placed on a electronic board). One skilled in the art would include grouping each individual set of electrodes or chip together because to examine each chip for any defects or misalignment to provide accurate inspection of the electronic device.

Tsujikawa does not disclose displaying means display the judgment result in connection with the data groups. It is well known in the art to display results on the monitor screen whether the electronic board is a defective or not defective. It would have been obvious to one having ordinary skill in the art at the time of the invention was made to include displaying results means because to make it known to the operator who is inspecting the electronic component so the operator can redo the inspection operation until the electronic board is error free improving the quality of manufacturing production.

With regards to claim 2, Tsujikawa discloses a printing inspection apparatus according to claim 1 wherein the grouping condition is determined based on a geometrical range

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on a printing surface of said substrate (see figure 8 and 9, the electronic board is rectangular and the geometrical range of the cream solders P1 – 3 are within the rectangular electrical board) and said printing judging means makes a judgment of the printing state using a data group grouped as an inspection performance range (see column 6 lines 29 to 36, judging means is whether the electronic board is defective or not defective).

With regards to claim 3, Tsujikawa discloses a printing inspection apparatus according to claim 1, wherein the grouping condition is determined based on an attribute of said electronic components (see figure 8 and 9, the electronic board is rectangular which has solder creams on three corners which is grouped within the rectangular board – attribute is the shape of the electronic board) and said printing judging means makes a judgment of the printing state using a data group grouped as an electronic component having an attribute specified as a subject to be inspected (see col. 6 lines 29 – 36 – judging means is whether the electronic board is defective or not defective).

With regards to claim 4, Tsujikawa discloses a printing inspection apparatus according to claim 1, wherein the grouping condition is determined so as to make a one-to-one correspondence between said electronic components and the data groups (see figure 9, data groups are P1 – 3 corresponds with electronic board 9) and said display means displays the judgment result for each data group (see column 6 lines 29 to 36, judging means is whether the electronic board is defective or not defective).

With regards to claim 5, see the rationale and rejection for claim 1.

With regards to claim 6, see the rationale and rejection for claim 2.

With regards to claim 7, see the rationale and rejection for claim 3.

With regards to claim 8, see the rationale and rejection for claim 4.

3. Claims 9 – 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsujikawa (US pat no 5,991,435) in view of Kishimoto ('224).

With regards to claim 9, Tsujikawa discloses a printing inspection data generating apparatus for generating inspection data used in a printing inspection apparatus for inspecting a printing state of cream solder on a substrate after screen printing and containing shape and position data indicating shapes and positions of solder print portions formed by printing the cream solder on a printing surface (see figure 1A), said printing inspection data generating apparatus comprising:

data providing means for providing element shape and position data indicating shapes and positions of element solder print portions formed on respective electrodes provided on a circuit forming surface of said substrate to be used to bond electronic components (see figure 10, points 82 – 85 are solder cream points which are assigned

position coordinates and the shapes indicated are shown in figure 17 a – c – triangle and rectangle).

Tsujikawa does not disclose grouping means for classifying and grouping the element position data into data groups which are grouped according to a grouping condition to identify at least one data group according to the grouping condition apart from other data group than the data group grouped.

Kishimoto reads on inspection data is generated by classifying and grouping solder element shape and position data corresponding to a plurality of patterns into at least one data group which is grouped according to a grouping condition apart from other data group, wherein the grouped data is identified by grouping condition (there are two different grouping condition discussed in Kishimoto; see figure 3 for first grouping condition, where a plurality of chips are grouped together; see figure 17, where each chip is group individually, discussed on column 5, lines 1 to 11, this grouping reads on the grouping conditions of the current invention, also chips inherently have electrodes/leads in order for them to be placed on a electronic board). One skilled in the art would include grouping each individual set of electrodes or chip together because to examine each chip for any defects or misalignment to provide accurate inspection of the electronic device.

With regards to claim 10, Tsujikawa discloses a printing inspection data generating apparatus according to claim 9, wherein the grouping condition is determined based on a geometrical range on the printing surface of said substrate (see figure 8 and 9, the

electronic board is rectangular and the geometrical range of the cream solders P1 – 3 are within the rectangular electrical board).

With regards to claim 11, Tsujikawa discloses a printing inspection data generating apparatus according to claim 9, wherein the grouping condition is determined based on an attribute of said electronic component (see figure 8 and 9, the electronic board is rectangular which has solder creams on three corners which is grouped within the rectangular board – attribute is the shape of the electronic board).

With regards to claim 12, Tsujikawa discloses a printing inspection data generating apparatus according to claim 9, wherein the grouping condition is determined so as to make one group for each of said electronic components (see figure 9, data groups are P1 – 3 corresponds with electronic board 9).

With regards to claim 13, Tsujikawa discloses a printing inspection data generating apparatus according to claim 9, further comprising specific inspection data giving means for giving specific inspection data to the individual data group (see column 10 lines 5 to 24, the specific inspection data is the amount of shift from current cream solder to next cream solder in x and / or y axis).

With regards to claim 14 / 9, Tsujikawa discloses Tsujikawa discloses a printing inspection data generating apparatus according to claim 9, wherein said data providing

means provides element shape and position data obtained based on mask opening data detected from a mask plate to be used for the screen printing (see figure 8 P1 – 3 are mask opening and cream solder are apply to each Q1 – 3, respectively, the mask plate is 9 in fig 8).

With regards to claims 14 / 10 – 13, see the rationale and rejection for claim 14 / 9.

With regards to claim 15, see the rationale and rejection for claim 9.

With regards to claim 16, see the rationale and rejection for claim 10.

With regards to claim 17, see the rationale and rejection for claim 11.

With regards to claim 18, see the rationale and rejection for claim 12.

With regards to claim 19, see the rationale and rejection for claim 13.

With regards to claim 20 / 15 – 19, see the rationale and rejection for claim 14 / 9.

Conclusion

This action is made final. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shorten statutory period for reply to this final action is set to expire three months from the mailing date of this action. In the event a first reply is filed within two months of the mailing date of this final action and the advisory action is not mailed until after the end of the three-month shorten statutory period, then the shorten statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however will the statutory period for reply expire later than six months from the mailing date of the final action


Any inquiry concerning this communication or earlier communications from the examiner should be directed to ALEX LIEW whose telephone number is (571)272-8623 or cell (917)763-1192. The examiner can be reached anytime.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew Bella can be reached on (571) 272-7778. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Matthew C Bella/
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7/25/08

<div>Application Number</div> <div></div>	Application/Control No.	Applicant(s)/Patent under Reexamination	
	10/626,140	FUKAGAWA ET AL.	
	Examiner	Art Unit	
	ALEX LIEW	2624	